



Quasi-Resonant 800 V CoolSET™ - in DSO-12 Package

Product Highlights

- Integrated 800 V avalanche rugged CoolMOS™
- Novel Quasi-Resonant operation and proprietary implementation for low EMI
- Enhanced Active Burst Mode with selectable entry and exit standby power
- Active Burst Mode to reach the lowest standby power <100 mW
- Fast startup achieved with cascode configuration
- Digital frequency reduction for better overall system efficiency
- Robust line protection with input OVP and brownout
- Comprehensive protection
- Pb-free lead plating, halogen free mold compound, RoHS compliant

Features

- Integrated 800 V avalanche rugged CoolMOS™
- Minimum switching frequency difference between low & high line for higher efficiency & better EMI
- Enhanced Active Burst Mode with selectable entry and exit standby power
- Active Burst Mode to reach the lowest standby power <100 mW
- Fast startup achieved with cascode configuration
- Digital frequency reduction up to 10 zero crossings
- Built-in digital soft start
- Cycle-by-cycle peak current limitation
- Maximum on/off time limitation to avoid audible noise during start up and power down
- Robust line protection with input OVP and brownout
- Auto restart mode protection for VCC Over Voltage, VCC Under Voltage, Over load/Open Loop, Line/Output Over Voltage, Over Temperature
- Limited charging current for VCC short to GND
- Pb-free lead plating, halogen free mold compound, RoHS compliant

Applications

- Auxiliary power supply for Home Appliances/white Goods, TV, PC & Server
- Blu-ray player, Set-top box & LCD/LED Monitor

Description

The Quasi-Resonant CoolSET[™]- (ICE5QRxx80BG) is the 5th generation of Quasi-Resonant integrated power IC optimized for off-line switch power supply in cascode configuration. It is housed in single package with 2 separate chips; one is controller chip and other is HV MOSFET chips. The IC can achieve lower EMI and higher efficiency with improved digital frequency reduction through the proprietary novel Quasi-Resonant operation. The enhanced Active Burst Mode enables flexibility in standby power range selection. The product has a wide operation range (10 ~ 25.5 V) of IC power supply and lower power consumption. The numerous protection functions including the robust line protection (both input OVP and brownout) to support the protections of the power supply system in failure situations. All of these make the CoolSET[™] (ICE5QRxx80BG) series an outstanding integrated power device in Quasi-Resonant flyback converter in the market.

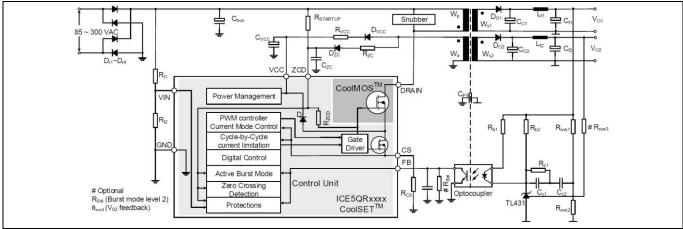


Figure 1 Typical application





Output Power of 5th generation Quasi-Resonant CoolSET™

Output Power of 5th generation Quasi-Resonant CoolSET™

Table 1 Output Power of 5th generation Quasi-Resonant CoolSET[™]

Туре	Package	Marking	V _{DS}		220V _{AC} ±20% ²	85-300 V _{AC²}
ICE5QR4780BG	PG-DSO-12	5QR4780BG	800 V	4.13 Ω	28 W	15 W
ICE5QR2280BG	PG-DSO-12	5QR2280BG	800 V	2.13 Ω	42 W	23 W
ICE5QR1680BG	PG-DSO-12	5QR1680BG	800 V	1.53 Ω	50 W	27 W
ICE5QR0680BG	PG-DSO-12	5QR0680BG	800 V	0.71 Ω	77 W	42 W

 $^{^{\}rm 1}$ Typ. at T_J =25°C (inclusive of low side MOSFET)

² Calculated maximum output power rating in an open frame design at T_a=50°C, T_J=125°C (integrated high voltage MOSFET) and using minimum drain pin copper area in a 2 oz copper single sided PCB. The output power figure is for selection purpose only. The actual power can vary depending on particular designs. Please contact to a technical expert from Infineon for more information.



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Pin Configuration and Functionality

1 Pin Configuration and Functionality

The pin configuration is shown in Figure 2 and the functions are described in Table 2.

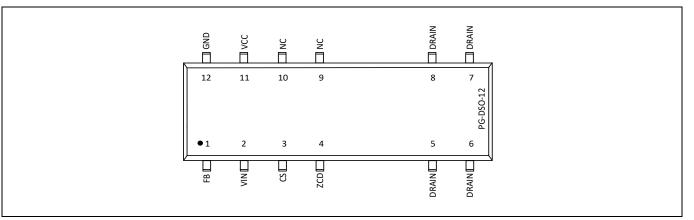


Figure 2 Pin Configuration

Table 2Pin Definitions and Functions

Pin	Symbol	Function					
1	FB	Feedback & Burst entry/exit control					
		FB pin combines the functions of feedback control, selectable burst entry/exit control and overload/open loop protection.					
2	VIN	Input Line OVP & Brownout					
		VIN pin is connected to the bus via resistor divider (see Figure 1) to sense the					
		line voltage. This pin combines the functions of input Line OVP, Brownout and minimum ZC count setting for low and high line.					
3	CS	Current Sense					
		The CS pin is connected to the shunt resistor for the primary current sensing externally and to the PWM signal generator block for switch-off determination (together with the feedback voltage) internally.					
4	ZCD	Zero Crossing Detection					
		ZCD pin combines the functions of start up, zero crossing detection and output over voltage protection. During the start up, it is used to provide a voltage level to the gate of power switch CoolMOS [™] to charge V _{cc} capacitor.					
5, 6, 7, 8	DRAIN	Drain					
		The DRAIN pin is connected to the drain of the integrated CoolMOS [™] .					
11	VCC	VCC(Positive Voltage Supply)					
		The VCC pin is the positive voltage supply to the IC. The operating range is					
		between V_{VCC_OFF} and V_{VCC_OVP} .					
12	GND	Ground					
		The GND pin is the common ground of the CoolSET™.					
9,10	NC	Not connected.					



Representative Block Diagram



Representative Block Diagram

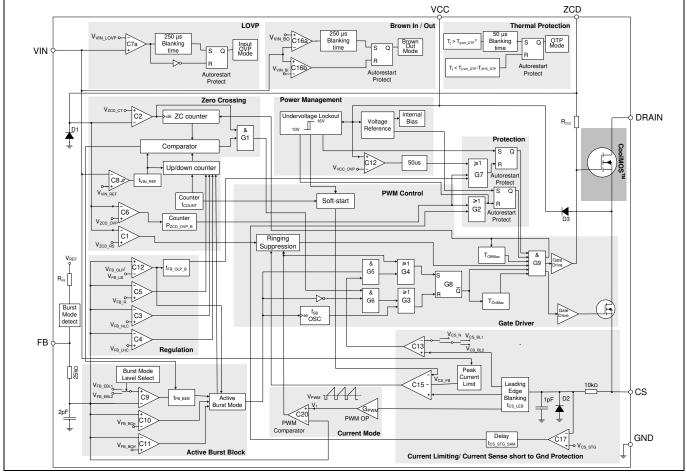


Figure 3 Representative Block Diagram

Note:

Junction temperature of the controller chip is sensed for over temperature protection. The CoolMOS™ is a separated chip from the controller chip in the same package. Please refer to the design guide and/or consult a technical expert from Infineon for the proper thermal design.



3 Functional Description

3.1 V_{cc} Pre-Charging and Typical V_{cc} Voltage during Start-up

As shown in Figure 1, once the line input voltage is applied, a rectified voltage appears across the capacitor $C_{BUS.}$ The pull up resistor $R_{STARTUP}$ provides a current to charge the C_{iss} (input capacitance) of CoolMOSTM and gradually generate one voltage level. If the voltage over C_{iss} is high enough, CoolMOSTM on and V_{CC} capacitor will be charged through primary inductance of transformer L_P , CoolMOSTM and internal diode D_3 with two steps constant current source $I_{VCC_Charge1}^1$ and $I_{VCC_Charge3}^1$.

A very small constant current source $(I_{VCC_Charge1})$ is charged to the V_{CC} capacitor till V_{CC} reach V_{CC_SCP} to protect the controller from V_{CC} pin short to ground during the start up. After this, the second step constant current source $(I_{VCC_Charge3})$ is provided to charge the V_{CC} capacitor further, until the V_{CC} voltage exceeds the turned-on threshold V_{VCC_ON} . As shown in the time phase I in Figure 4, the V_{CC} voltage increase almost linearly with two steps.

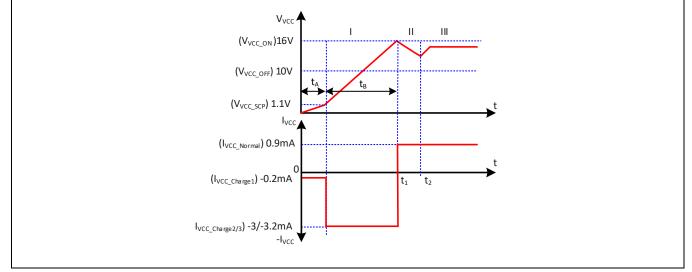


Figure 4 VCC voltage and current at start up

The time taking for the V_{cc} pre-charging can then be approximately calculated as:

$$t_{1} = t_{A} + t_{B} = \frac{V_{VCC_SCP} \cdot C_{VCC}}{I_{VCC_Charge1}} + \frac{(V_{VCC_ON} - V_{VCC_SCP}) \cdot C_{VCC}}{I_{VCC_Charge3}}$$
(1)

When the V_{cc} voltage exceeds the V_{cc} turned on threshold V_{vcc_ON} at time t₁, the IC begins to operate with soft start. Due to power consumption of the IC and the fact that there is still no energy from the auxiliary winding to charge the V_{cc} capacitor before the output voltage is built up, the V_{cc} voltage drops (Phase II). Once the output voltage is high enough, the V_{cc} capacitor receives the energy from the auxiliary winding from the time t_2 onward and delivering the I_{Vcc_Normal}² to the CoolSETTM. The V_{cc} then will reach a constant value depending on output load.

3.2 Soft-start

As shown in Figure 5, at the time t_{on} , the IC begins to operate with a soft-start. By this soft-start the switching stresses for the MOSFET, diode and transformer are minimized. The soft-start implemented in ICE5QRxx80BG is a digital time-based function. The preset soft-start time is t_{ss} (12 ms) with 4 steps. If not limited by other functions, the peak voltage on CS pin will increase step by step from 0.3 V to 1 V finally. During the first 3 ms of soft start, the ringing suppression time is set to 25 μ s to avoid irregular switching due to switch off oscillation noise.

 $^{^1}$ $\mathsf{I}_{\mathsf{VCC_Charge1/2/3}}$ is charging current from the controller to V_{CC} capacitor during start up

² I_{VCC_Normal} is supply current from V_{CC} capacitor or auxiliary winding to the CoolSET[™] during normal operation



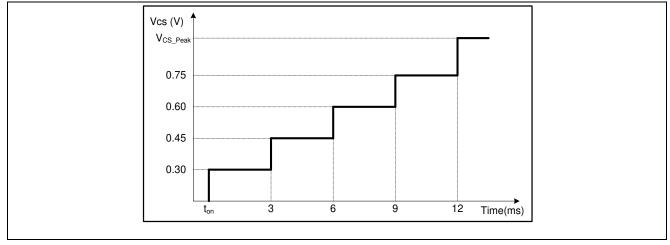


Figure 5 Maximum current sense voltage during soft start

3.3 Normal Operation

During normal operation, the ICE5QRxx80BG works with a digital signal processing circuit composing an up/down counter, a zero-crossing counter (ZC counter) and a comparator, and an analog circuit composing a current measurement unit and a comparator. The switch-on and -off time points are each determined by the digital circuit and the analog circuit, respectively. The input information of the zero-crossing signal and the value of the up/down counter are needed to determine the switch-on while the feedback signal V_{FB} and the current sensing signal V_{CS} are necessary for the switch-off determination. Details about the full operation of the CoolSET[™] in normal operation are illustrated in the following paragraphs.

3.3.1 Digital Frequency Reduction

As mentioned above, the digital signal processing circuit consists of an up/down counter, a ZC counter and a comparator. These three parts are key to implement digital frequency reduction with decreasing load. In addition, a ringing suppression time controller is implemented to avoid mis-triggering by the high frequency oscillation when the output voltage is very low under conditions such as soft start period or output short circuit. Functionality of these parts is described as in the following.

3.3.1.1 Minimum ZC Count Determination

To reduce the switching frequency difference between low and high line, minimum ZC count determination is implemented. Minimum ZC count is set to 1 if VIN less than V_{VIN_REF} which represents for low line. For high line, minimum ZC count is set to 3 after VIN higher than V_{VIN_REF} . There is also a hysteresis V_{VIN_REF} with certain blanking time t_{VIN_REF} for stable AC line selection between low and high line.

3.3.1.2 Up/down counter

The up/down counter stores the number of the zero crossing which determines valley numbers to switch-on the main MOSFET after demagnetization of the transformer. This value is fixed according to the feedback voltage, V_{FB} , which contains information about the output power. Indeed, in a typical peak current mode control, a high output power results in a high feedback voltage, and a low output power leads to a low feedback voltage. Hence, according to V_{FB} , the value in the up/down counter is changed to vary the power MOSFET off-time according to the output power. In the following, the variation of the up/down counter value according to the feedback voltage is explained.



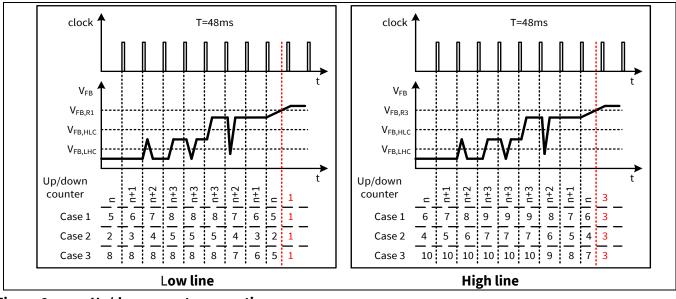
The feedback voltage V_{FB} is internally compared with three threshold voltages V_{FB_LHC} , V_{FB_HLC} and V_{FB_R} at each clock period of 48 ms. The up/down counter counts then upward, keep unchanged or count downward, as shown in Table 3.

Table 3Operation of up/down counter

V _{FB}	up/down counter action
Always lower than V _{FB_LHC}	Count upwards till n=8/10 ¹
Once higher than $V_{F_{LHC}}$, but always lower than $V_{FB_{-HLC}}$	Stop counting, no value changing
Once higher than $V_{FB_{HLC}}$, but always lower than $V_{FB_{R}}$	Count downwards till n=1/3 ²
Once higher than V_{FB_R}	Set up/down counter to n=1/3 ²

The number of zero crossing is limited and therefore, the counter varies among 1 to 8 (for low line) or 3 to 10 (for high line) and any attempt beyond this range is ignored. When V_{FB} exceeds V_{FB_R} voltage, the up/down counter is reset to 1 (low line) and 3 (high line) in order to allow the system to react rapidly to a sudden load increase. The up/down counter value is also reset to 1 (low line) and 3 (high line) at the start-up time, to ensure an efficient maximum load start up. Figure 6 shows some examples on how up/down counter is changed according to the feedback voltage over time.

The use of two different thresholds V_{FB_LHC} and V_{FB_HLC} to count upward or downward is to prevent frequency jittering when the feedback voltage is close to the threshold point.





3.3.1.3 Zero crossing (ZC counter)

In the system, the voltage from the auxiliary winding is applied to the ZCD pin through a RC network, which provides a time delay to the voltage from the auxiliary winding. Internally this pin is connected to a negative clamping network, a zero-crossing detector, an output overvoltage detector and a ringing suppression time controller.

During on-state of the power switch, a positive gate drive voltage is applied to the ZCD pin due to R_{ZCD} resistor, hence external diode D_{ZC} (see Figure 1) is added to block the negative voltage from the auxiliary winding. The ZC counter has a minimum value of 1 (for low line) or 3 (for high line) and maximum value of 8 (for low line) or 10 (for high line). After the internal high voltage CoolMOS[™] is turned off, every time when the falling voltage

¹ n=8 (for low line) and n=10 (for high line)

ramp of on ZCD pin crosses the V_{ZCD_CT} threshold, a zero crossing is detected and ZC counter will increase by 1. It is reset every time after the DRIVER output is changed to high.

To achieve the switch on at voltage valley, the voltage from the auxiliary winding is fed to a time delay network (the RC network consists of R_{zc} and C_{zc} as shown in Figure 1) before it is applied to the zero-crossing detector through the ZCD pin. The needed time delay to the main oscillation signal Δt should be approximately one fourth of the oscillation period, T_{osc} (by transformer primary inductor and drain-source capacitor) minus the propagation delay from the detected zero-crossing to the switch-on of the main switch t_{delay} , theoretically:

$$\Delta t = \frac{T_{OSC}}{4} - t_{delay} \tag{2}$$

This time delay should be matched by adjusting the time constant of the RC network which is calculated as:

 $\tau_{\rm td} = C_{ZC} \cdot \frac{R_{ZC} \cdot R_{ZCD}}{R_{ZC} + R_{ZCD}}$

3.3.2 Ringing suppression time

After CoolMOSTM is turned off, there will be some oscillation on V_{DS} , which will also appear on V_{ZCD} . To avoid mistriggering by such oscillations to turn on the CoolMOSTM, a ringing suppression timer is implemented. This suppression time is depended on the voltage V_{ZCD} . If the voltage V_{ZCD} is lower than the threshold $V_{ZCD_{RS}}$, a longer preset time $t_{ZCD_{RS2}}$ is applied. However, if the voltage V_{ZCD} is higher than the threshold, a shorter time $t_{ZCD_{RS1}}$ is set.

3.3.2.1 Switch on determination

After the gate drive goes to low, it cannot be changed to high during ring suppression time. After ring suppression time, the gate drive can be turned on when the ZC counter value is equal to up/down counter value.

However, it is also possible that the oscillation between primary inductor and drain-source capacitor damps very fast and IC cannot detect zero crossings event. In this case, a maximum off time is implemented. After gate drive has been remained off for the period of T_{OffMax} , the gate drive will be turned on again regardless of the ZC counter values and V_{ZCD} . This function can effectively prevent the switching frequency from going lower than 20 kHz. Otherwise it will cause audible noise.

3.3.3 Switch off determination

In the converter system, the primary current is sensed by an external shunt resistor, which is connected between the internal low side MOSFET and the common ground. The sensed voltage across the shunt resistor V_{CS} is applied to an internal current measurement unit, and its output voltage V_1 is compared with the feedback voltage V_{FB} . Once the voltage V_1 exceeds the voltage V_{FB} , the output flip-flop is reset. As a result, the main power switch is switched off. The relationship between the V_1 and the V_{CS} is described by (see Figure 3):

$$V_{CS} = I_D \times R_{CS}$$

$$V_1 = G_{PWM} \cdot V_{CS} + V_{PWM}$$
(4)
where, V_{CS} : CS pin voltage

$$I_D$$
 : power MOSFET current

$$R_{CS}$$
 : resistance of the current sense resistor

$$V_1$$
 : voltage level compared to V_{FB}

$$G_{PWM}$$
 : PWM-OP gain



(3)



To avoid mis-triggering caused by the voltage spike across the shunt resistor at the turn on of the main power switch, a leading edge blanking time, t_{LEB} , is applied to the output of the comparator. In other words, once the gate drive is turned on, the minimum on time of the gate drive is the leading edge blanking time.

In addition, there is a maximum on time, t_{OnMax} , limitation implemented in the IC. Once the gate drive has been in high state longer than the maximum on time, it will be turned off to prevent the switching frequency from going too low because of long on time.

Also, if the voltage at the current sense pin is lower than the preset threshold $V_{CS_{STG}}$ after the time $t_{CS_{STG}_{SAM}}$ for three consecutive pulses during on-time of the power switch, this abnormal V_{CS} will trigger IC into auto restart mode.

3.3.4 Modulated gate drive

The drive-stage is optimized for EMI consideration. The switch on speed is slowed down before it reaches the CoolMOS[™] turn on threshold. That is a slope control of the rising edge at the output of driver (see Figure 7). Thus the leading switch spike during turn on is minimized.

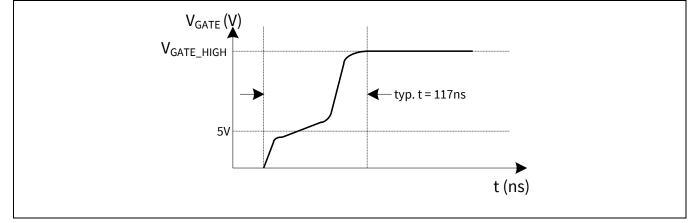


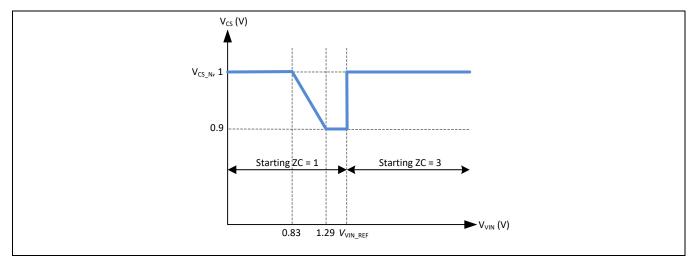
Figure 7 Gate rising waveform

3.4 Current limitation

There is a cycle by cycle current limitation realized by the current limit comparator to provide over-current detection. The source current of the CoolMOS[™] is sensed via a sense resistor R_{cs}. By means of R_{cs} the source current is transformed to a sense voltage V_{cs} which is fed into the pin CS. If the voltage V_{cs} exceeds an internal voltage limit, adjusted according to the Line voltage, the comparator immediately turns off the gate drive. When the main bus voltage increases, the switch on time becomes shorter and therefore the operating frequency is also increased. As a result, for a constant primary current limit, the maximum possible output power is increased which is beyond the converter design limit.

To compensate such effect, both the internal peak current limit circuit (V_{cs}) and the ZC count varies with the bus voltage according to Figure.







3.5 Active Burst Mode with selectable power level

At light load condition, the IC enters Active Burst Mode operation to minimize the power consumption. Details about Active Burst Mode operation are explained in the following paragraphs.

The burst mode entry level can be selected by changing the different resistor R_{Sel} at FB pin. There are 2 levels to be selected with different resistor which are targeted for low range of Active Burst Mode power (Level 1) and high range of Active Burst Mode power (Level 2). The following table shows the control logic for the entry and exit level with the FB voltage.

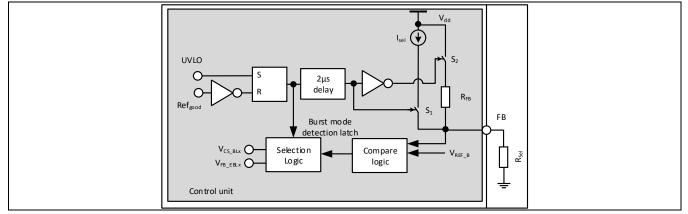
Table 4	Two levels	entry and exit Active Bu	urst Mode power

Level	V _{FB}	V _{cs}	Entry level	Exit level
			V _{FB_EBLX}	V _{FB_LB}
1	$V_{FB} > V_{REF_B}$	$V_{CS_{BL1}} = 0.31 V$	0.90 V	2.75 V
2	$V_{FB} < V_{REF_B}$	V _{CS_BL2} = 0.35 V	1.05 V	2.75 V

During IC first startup, the internal Ref_{GOOD} signal is logic low when $V_{CC} < 4 V$. It will reset the Burst Mode level Detection latch. When the Burst Mode Level Detection latch is low and IC is in OFF state, the IC internal R_{FB} resistor is disconnected from the FB pin and a current source I_{sel} is turned on instead.

From V_{cc}=4 V to V_{cc} on threshold, the FB pin will start to charge to a voltage level associated with R_{Sel} resistor. When V_{cc} reaches V_{cc} on threshold, the FB voltage is sensed. The burst mode thresholds are then chosen according to the FB voltage level. The Burst Mode Level Detection latch is then set to high. Once the detection latch is set high, any change of the FB level will not change the threshold selection. The current source I_{sel} is turned off in 2 µs after V_{cc} reaches V_{cc} on threshold and the R_{FB} resistor is re-connected to FB pin (see Figure 9).







3.5.1 Entering Active Burst Mode Operation

For determination of entering Active Burst Mode operation, three conditions apply:

- the feedback voltage is lower than the threshold of V_{FB_EBLX}
- the up/down counter is 8 for low line or 10 for high line and
- the above two conditions remain after a certain blanking time t_{FB_BEB} (20 ms)

Once all of these conditions are fulfilled, the Active Burst Mode flip-flop is set and the controller enters Active Burst Mode operation. This multi-condition determination for entering Active Burst Mode operation prevents mis-triggering of entering Active Burst Mode operation, so that the controller enters Active Burst Mode operation only when the output power is really low during the preset blanking time.

3.5.2 During Active Burst Mode Operation

After entering the Active Burst Mode the feedback voltage rises as V_0 starts to decrease due to the inactive PWM section. One comparator observes the feedback signal if the voltage level V_{FB_BON} is exceeded. In that case the internal circuit is power up to restrart with switching.

Turn-on of the power MOSFET is triggered by ZC counter with a fixed value of 8 ZC for low line and 10 ZC for high line. Turn-off is resulted if the voltage across the shunt resistor at CS pin hits the threshold V_{CS_BLX} . If the output load is still low, the feedback signal decreases as the PWM section is operating. When feedback signal reaches the low threshold V_{FB_BOff} , the internal circuit is reset again and the PWM section is disabled until next time V_{FB} signal increases beyond the V_{FB_BOff} threshold. In Active Burst Mode, the feedback signal is changing like a saw tooth between V_{FB_BOff} and V_{FB_BOff} (see Figure 10).

3.5.3 Leaving Active Burst Mode Operation

The feedback voltage immediately increases if there is a high load jump. This is observed by a comparator with threshold of V_{FB_LB} . As the current limit is V_{CS_BLX} (31% or 35%) during Active Burst Mode, a certain load is needed so that feedback voltage can exceed V_{FB_LB} . After leaving Active Burst Mode, Gate will only turn on if zero crossing is detected ($V_{ZCD} < V_{ZCD_LB}$) to ensure full transformer demagnetization. This eases synchronous rectification implementation by ensuring DCM operation upon exit of burst mode. Then, normal peak current control through V_{FB} is re-activated. In addition, the up/down counter will be set to 1 (low line) or 3 (high line) immediately after leaving Active Burst Mode. This is helpful to minimize the output voltage undershoot.



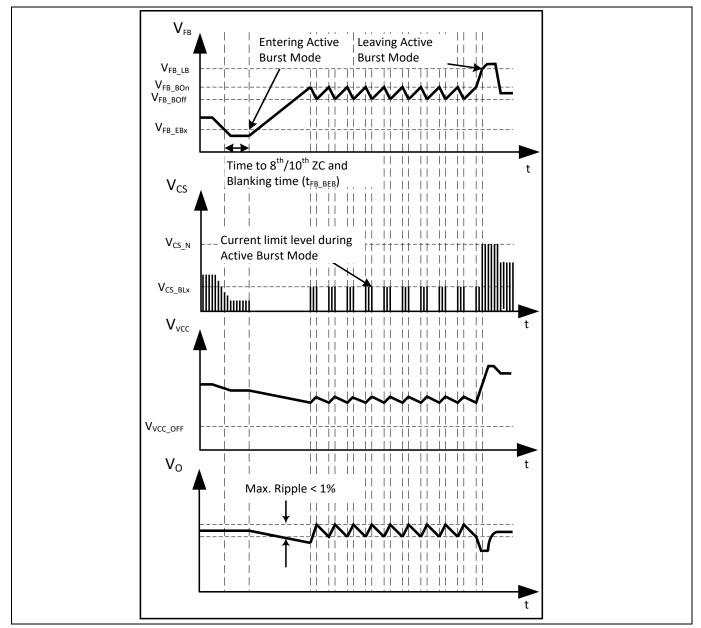


Figure 10 Signals in Active Burst Mode

3.6 Protection Functions

The ICE5QRxx80BG provides numerous protection functions which considerably improve the power supply system robustness, safety and reliability. The following table summarizes these protection functions. There are 3 different kinds of protection mode; non switch auto restart, auto restart and odd skip auto restart. The details can refer to the Figure 11, Figure 12 and Figure 13.

Table 5	Protection functions
---------	----------------------

Protection Functions	Normal Mode	Burst Mode		Protection Mode	
		Burst ON	Burst OFF		
Line Over Voltage	V	v	V	Non switch Auto Restart	
Brownout	V	V	V	Non switch Auto Restart	



Protection Functions	Normal Mode	Burs	t Mode	Protection Mode	
		Burst ON	Burst OFF		
V _{cc} Over Voltage	v	V	NA ¹	Odd skip Auto Restart	
V _{cc} Under Voltage	V	V	V	Auto Restart	
Over Load	V	NA ¹	NA^1	Odd skip Auto Restart	
Output Over Voltage	V	V	NA^1	Odd skip Auto Restart	
Over Temperature	V	V	V	Non switch Auto Restart	

3.6.1 Line Over Voltage

The AC **Line Over Voltage** Protection is detected by sensing bus capacitor voltage through VIN pin via 2 potential divider resistors, R_{l1} and R_{l2} (see Figure 1). Once V_{VIN} voltage is higher than the line over voltage threshold V_{VIN_LOVP} , the controller enters Line Over Voltage Protection and it releases the protection mode after V_{VIN} is lower than V_{VIN_LOVP} .

3.6.2 Brownout

The **Brownout** protection is observed by VIN pin similar to line over voltage Protection method with a different voltage threshold level. When V_{VIN} voltage is lower than the brownout threshold (V_{VIN_BO}), the controller enters Brownout Protection and it releases the protection mode after V_{VIN} higher than brownin threshold (V_{VIN_BO}).

3.6.3 V_{cc} Over Voltage or Under Voltage

During operation, the V_{cc} voltage is continuously monitored. In case of a **V_{cc} Over Voltage** or **Under Voltage**, the IC is reset and the main power switch is then kept off. After the V_{cc} voltage falls below the threshold V_{Vcc_OFF}, the new start up sequence is activated. The V_{cc} capacitor is then charged up. Once the voltage exceeds the threshold V_{vcc_ON}, the IC begins to operate with a new soft-start.

3.6.4 Over Load

In case of open control loop or output **Over Load**, the feedback voltage will be pulled up and exceed V_{FB_OLP} . After a blanking time of $t_{FB_OLP_B}$, the IC enters auto restart mode. The blanking time here enables the converter to operate for a certain time during a sudden load jump.

3.6.5 Output Over Voltage

During off-time of the power MOSFET, the voltage at the ZCD pin is monitored for **Output Over Voltage** detection. If the voltage is higher than the preset threshold V_{ZCD_OVP} for 10 consecutive pulses, the IC enters Output Over Voltage Protection.

3.6.6 Over Temperature

If the junction temperature of controller chip exceeds T_{jcon_OTP}, the IC enters into **Over Temperature** protection (OTP) auto restart mode. The controller implements with a 40 °C hysteresis. In another word, the controller/IC can only resume from OTP if its junction temperature drops 40 °C from OTP trigger point. Please be noted that the separated CoolMOS[™] chip may have different temperature (mostly higher) from the controller chip.



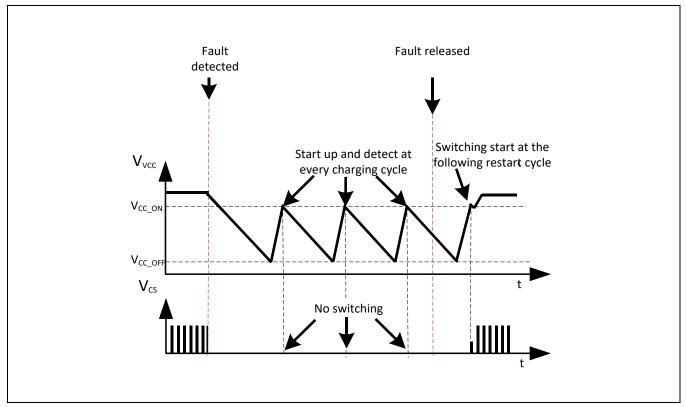
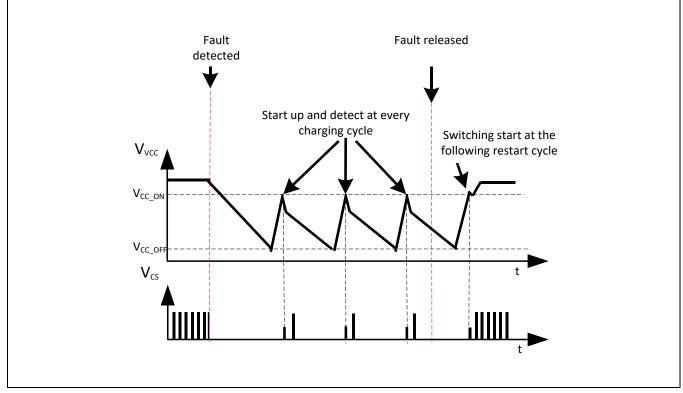
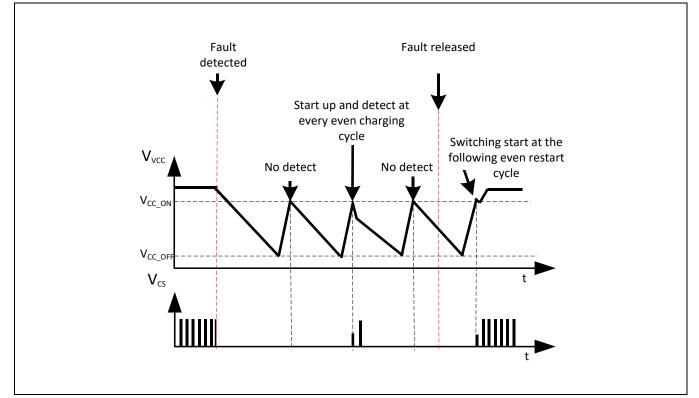


Figure 11 Non switch Auto Restart Mode













4 Electrical Characteristics

Attention: All voltages are measured with respect to ground (Pin12). The voltage levels are valid if other ratings are not violated.

4.1 Absolute Maximum Ratings

Attention: Stresses above the maximum values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit. System design needs to ensure not to exceed the maximum limit. Ta=25°C unless otherwise specified.

Parameter	Symbol	Limit Values		Unit	Note / Test Condition
		Min.	Max.		
Drain Source Voltage (CoolMOS™)	V _{DS}			V	T _j = 25 °C
ICE5QRxx80BG		-	800		
Pulse drain current	I _{D_Pulse}			А	
ICE5QR4780BG ¹		-	2.6		
ICE5QR2280BG ²		-	5.8		
ICE5QR1680BG ²		-	5.8		
ICE5QR0680BG ²		-	5.8		
Avalanche energy, repetitive,	E _{AR}			mJ	
t _{AR} limited by max. T _J =150°C with					
T _{J,Start} =25°C					
ICE5QR4780BG		-	0.02		I _D =0.2 A, V _{DD} =50 V
ICE5QR2280BG		-	0.05		I _D =0.4 A, V _{DD} =50 V
ICE5QR1680BG		-	0.07		I _D =0.6 A, V _{DD} =50 V
ICE5QR0680BG		-	0.22		I _D =1.8 A, V _{DD} =50 V
Avalanche current, repetitive,	I _{AR}			А	
t _{AR} limited by max. T _J =150°C with					
T _{J,Start} =25°C					
ICE5QR4780BG		-	0.2		
ICE5QR2280BG		-	0.4		
ICE5QR1680BG		-	0.6		
ICE5QR0680BG		-	1.8		
VCC Supply Voltage	V _{cc}	-0.3	27.0	V	
FB Voltage	V_{FB}	-0.3	3.6	V	
ZCD Voltage	V _{ZCD}	-0.3	27	V	
CS Voltage	V _{cs}	-0.3	3.6	V	

Table 6 Absolute Maximum Ratings

Datasheet

 $^{^1}$ Pulse width t_{P} limited by $T_{j,\text{Max}}$

 $^{^2}$ Pulse width t_{P} =20 μs and limited by $T_{j,Max}$

Quasi-Resonant 800 V CoolSET[™] - in DSO-12 Package



Electrical Characteristics

VIN Voltage	V _{IN}	-0.3	3.6	V	
Maximum DC current on any pin except DRAIN & CS pins		-10.0	10.0	mA	
ESD robustness HBM	$V_{\text{ESD}_{\text{HBM}}}$	-	2000	V	According to EIA/JESD22
ESD robustness CDM	V _{ESD_CDM}	-	500	V	
Junction temperature range	TJ	-40	150	°C	Controller & CoolMOS
Storage Temperature	T _{STORE}	-55	150	°C	
Thermal Resistance (Junction- Ambient) ICE5QR4780BG ICE5QR2280BG ICE5QR1680BG	R _{thJA}		105 98 95	K/W	Setup according to the JESD51 standard and using minimum drain pin copper area in a 2 oz copper single sided PCB
ICE5QR0680BG		-	93 94		

4.2 Operating Range

Note: Within the operating range the IC operates as described in the functional description.

Table 7Operating Range

Parameter	Symbol	Limit Va	ues	Unit	Remark
		Min.	Max.		
VCC Supply Voltage	V _{vcc}	$V_{\rm VCC_OFF}$	V _{VCC_OVP}		
Junction Temperature of controller	T _{jCon_op}	-40	Т _{jCon_ОТР}	°C	Max value limited due to OTP of controller chip
Junction Temperature of CoolMOS	T _{jCoolMOS_op}	-40	150	°C	

4.3 **Operating Conditions**

Note: The electrical characteristics involve the spread of values within the specified supply voltage and junction temperature range T_J from – 40 °C to 125 °C. Typical values represent the median values, which are related to 25 °C. If not otherwise stated, a supply voltage of V_{cc} = 18 V is assumed.

Table 8Operating Conditions

Parameter	Symbol	Limit Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
VCC Charge Current	Ivcc_Charge1	-0.35	-0.2	-0.09	mA	V_{vcc} =0V, $R_{startUp}$ =50M Ω and V_{DRAIN} =90V
	Ivcc_Charge2	-	-3.2	-	mA	V_{vcc} =3V, $R_{startUp}$ =50M Ω and V_{DRAIN} =90V
	Ivcc_Charge3	-5	-3	-1	mA	$V_{\text{VCC}}\text{=}15\text{V}, R_{\text{StartUp}}\text{=}50\text{M}\Omega$ and $V_{\text{DRAIN}}\text{=}90\text{V}$
Current Consumption, Startup Current	I _{VCC_Startup}	-	0.19	-	mA	V _{vcc} =15V

Quasi-Resonant 800 V CoolSET[™] - in DSO-12 Package



Electrical Characteristics

Current Consumption, Normal	I _{VCC_Normal}	-	0.9	-	mA	I _{FB} =0A (No gate switching)
Current Consumption, Auto Restart	I _{VCC_AR}	-	320	-	μΑ	
Current Consumption, Burst Mode	I _{VCC_Burst Mode}	-	0.5	-	mA	V _{FB} =1.8V
VCC Turn-on Threshold Voltage	Vvcc_on	15.3	16	16.5	V	
VCC Turn-off Threshold Voltage	VVCC_OFF	9.5	10	10.5	V	
VCC Short Circuit Protection	V _{VCC_SCP}	-	1.1	1.9	V	
VCC Turn-off blanking	$t_{\text{VCC_OFF_B}}$	-	50	-	μs	

4.4 Internal Voltage Reference

Table 9Internal Voltage Reference

Parameter	Symbol	Limit Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Internal Reference Voltage	V _{ref}	3.2	3.3	3.39	v	Measured at pin FB I _{FB} =0

4.5 **PWM Section**

Table 10PWM Section

Parameter	Symbol	Limit V	/alues		Unit	Note / Test Condition
		Min.	Тур.	Max.		
Feedback Pull-Up Resistor	R _{FB}	11	15	20	kΩ	
PWM-OP Gain	G _{PWM}	1.95	2.05	2.15	-	
Offset for Voltage Ramp	V _{PWM}	0.42	0.5	0.58	V	
Maximum on time in normal operation	t _{OnMax}	20	35	60	μs	
Maximum off time in normal operation	t _{OffMax}	24	42.5	71	μs	

4.6 Current Sense

Table 11Current Sense

Parameter	Symbol	Limit V	/alues		Unit	Note / Test Condition
		Min.	Тур.	Max.		
Peak current limitation in normal operation	V _{CS_N}	0.94	1.00	1.06	V	
Leading Edge Blanking time	t_{CS_LEB}	118	220	462	ns	
Peak Current Limitation in Active Burst Mode – Level 1	V _{CS_BL1}	0.26	0.31	0.36	V	
Peak Current Limitation in Active Burst Mode – Level 2	V _{CS_BL2}	0.3	0.35	0.4	V	
Abnormal CS voltage threshold	V _{cs_stg}	0.06	0.10	0.15	V	



Abnormal CS voltage Consecutive Trigger	P _{CS_STG}	-	3	-	cycle	
Abnormal CS voltage Sample period	tcs_stg_sam	2.3	5	-	μs	

4.7 Soft Start

Table 12 Soft Start

Parameter	Symbol	Limit \	/alues		Unit	Note / Test Condition
		Min.	Тур.	Max.		
Soft-Start time	$t_{\rm SS}$	8.5	12	-	ms	
Soft-start time step	$t_{SS_s^1}$	-	3	-	ms	
Internal regulation voltage at first step	V _{SS1} ¹	-	0.30	-	V	CS peak voltage
Internal regulation voltage step at soft start	V _{SS_S} ¹	-	0.15	-	V	CS peak voltage

4.8 Digital Zero Crossing

Table 13 Digital Zero Crossing

Parameter	Symbol	Limit V	alues		Unit	Note / Test Condition
		Min.	Тур.	Max.]	
Zero crossing threshold voltage	V _{ZCD_CT}	60	100	150	mV	
Zero crossing Ringing suppression threshold	V _{ZCD_RS}	-	0.45	-	V	
Minimum ringing suppression time	t _{ZCD_RS1}	1.5	2.5	4.1	μs	$V_{ZCD} > V_{ZCD,RS}$
Maximum ringing suppression time	$t_{\rm ZCD_RS2}$	-	25.00	-	μs	V _{ZCD} < V _{ZCD,RS}
Threshold to reset Up/Down Counter	V _{FB_R}	-	2.80	-	V	
Threshold for downward counting	$V_{\rm FB_HLC}$	-	2.05	-	V	
Threshold for upward counting	V _{FB_LHC}	-	1.55	-	V	
Counter Time	t _{count}	-	48	-	ms	
ZCD resistance	R _{zcd}	2.5	3.0	3.5	kΩ	Internal resistor at ZCD pin
VIN voltage threshold for line selection	V _{VIN_REF}	1.48	1.52	1.58	V	
Blanking time for VIN voltage threshold for line selection	t _{vin_ref}	-	16.00	-	ms	

¹ The parameter is not subjected to production test - verified by design/characterization Datasheet 21 of 39



4.9 Active Burst Mode

Table 14Active Burst Mode

Parameter	Symbol	Limit V	alues		Unit	Note / Test Condition
		Min.	Тур.	Max.]	
Charging current to select burst mode	I _{sel}	2.1	3	3.9	μA	
Burst mode selection reference voltage	V _{REF_B}	2.65	2.75	2.85	V	
Feedback voltage for entering Active Burst Mode for level 1	V _{FB_EBL1}	0.86	0.90	0.94	V	
Feedback voltage for entering Active Burst Mode for level 2	V _{FB_EBL2}	1.0	1.05	1.1	V	
Blanking time for entering Active Burst Mode	t _{fb_beb}	-	20	-	ms	
Feedback voltage for leaving Active Burst Mode	$V_{\rm FB_LB}$	2.65	2.75	2.85	V	
ZCD voltage threshold for first pulse after leaving Active Burst Mode	V _{ZCD_LB}	60	100	150	mV	
Feedback voltage for burst-on	$V_{\rm FB_BOn}$	2.3	2.40	2.5	V	
Feedback voltage for burst-off	$V_{\rm FB_BOff}$	1.9	2.00	2.1	V	

4.10 Line Over Voltage Protection

Table 15 Line OVP

Parameter	Symbol	ol Limit Values				Note / Test Condition
		Min.	Тур.	Max.		
Line Over Voltage threshold	V _{VIN_LOVP}	2.8	2.9	3.0	V	
Line Over Voltage Blanking	$t_{\text{VIN}_\text{LOVP}_\text{B}}$	-	250	-	μs	

4.11 Brownout Protection

Table 16Brownout Protection

Parameter	Symbol	Limit	Values		Unit	Note / Test Condition
		Min.	Тур.	Max.		
BrownIn threshold	$V_{\rm VIN_BI}$	0.63	0.66	0.69	V	
BrownIn Blanking	t _{vin_bi_b}	-	250	-	μs	
BrownOut threshold	$V_{VIN_{BO}}$	0.37	0.40	0.43	V	
BrownOut Blanking	t _{vin_bo_b}	-	250	-	μs	

4.12 V_{cc} Over Voltage Protection

Table 17Vcc Over Voltage Protection



Parameter	Symbol	Limit Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		Note / Test Condition
VCC Over Voltage threshold	V _{VCC_OVP}	24	25.50	27	V	
VCC Over Voltage blanking	t _{vcc_ovp_b}	-	50.00	-	μs	

4.13 Over Load Protection

Table 18Overload Protection

Parameter	Symbol	Limit Values			Unit	Note / Test Condition
		Min.	Тур.	Max.]	
Over Load Detection threshold for OLP protection at FB pin	V _{fb_olp}	2.65	2.75	2.85	V	
Over Load Protection Blanking Time	t _{fb_olp_b}	-	30	-	ms	

4.14 Output Over Voltage Protection

Table 19Output OVP

Parameter	Symbol	Limit Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Output Over Voltage threshold	V _{ZCD_OVP}	1.9	2.0	2.1	V	
Output Over Voltage Blanking Pulse	P _{ZCD_OVP_B}	-	10	-	pulse	Consecutive Pulse

4.15 Thermal Protection

Table 20Thermal Protection

Parameter	Symbol	Limit Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Over temperature protection ¹	$T_{\rm jcon_OTP}$	129	140	150	°C	Junction temperature of the controller chip (not the CoolMOS™ chip)
Over temperature Hysteresis	T _{jhys_otp}	-	40	-	°C	
Over temperature Blanking Time	$t_{ m jcon_OTP_B}$	-	50	-	μs	

 ¹ The parameter is not subjected to production test - verified by design/characterization
 Datasheet 23 of 39



4.16 CoolMOS[™] Section

Table 21ICE5QRxx80BG

Parameter	Symbol	Limit Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Drain Source Breakdown Voltage	V _{(BR)DSS}				V	<i>T</i> _j = 25°C
ICE5QRxx80BG		800	-	-		
Drain to CS On-Resistance (inclusive	R _{DSon}				Ω	
of low side MOSFET)						
ICE5QR4780BG		-	4.13	4.85		<i>T</i> j = 25°C
		-	8.69 ¹	-		<i>T</i> j=125°C, <i>I</i> _D =0.4A
ICE5QR2280BG		-	2.13	2.35		<i>T</i> j = 25°C
		-	4.31 ¹	-		<i>T</i> j=125°C, <i>I</i> _D =1A
ICE5QR1680BG		-	1.53	1.75		<i>T</i> j = 25°C
		-	3.01 ¹	-		<i>T</i> j=125°C, / _D =1.4A
ICE5QR0680BG		-	0.71	0.80		<i>T</i> j = 25°C
		-	1.27 ¹	-		<i>T</i> j=125°C, <i>I</i> _D =2A
Effective output capacitance, energy	C _{o(er)}				рF	V _{GS} =0V, V _{DS} =0~500V
related ¹						
ICE5QR4780BG		-	3	-		
ICE5QR2280BG		-	7	-		
ICE5QR1680BG		-	8	-		
ICE5QR0680BG		-	24	-		
Rise Time ²	t _{rise}	-	30	-	ns	
Fall Time ²	$t_{\rm fall}$	-	30	-	ns	

¹The parameter is not subjected to production test - verified by design/characterization

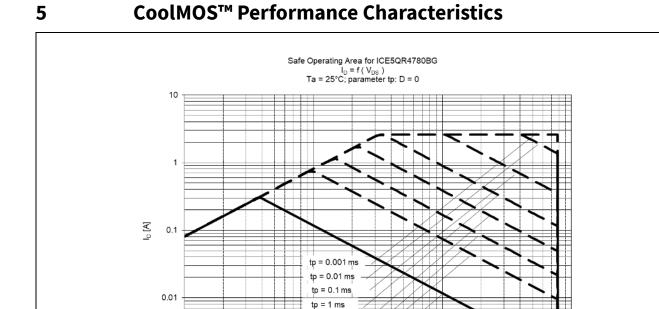
²Measured in a Typical Flyback Converter Application



CoolMOS[™] Performance Characteristics

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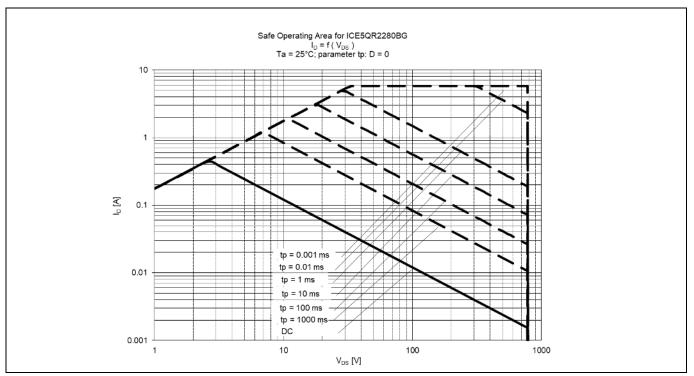
1



tp = 10 ms tp = 100 ms tp = 1000 ms DC

10

Figure 14 Safe Operating Area (SOA) curve for ICE5QR4780BG



V_{DS} [V]

100

1000

Figure 15 Safe Operating Area (SOA) curve for ICE5QR2280BG



CoolMOS[™] Performance Characteristics

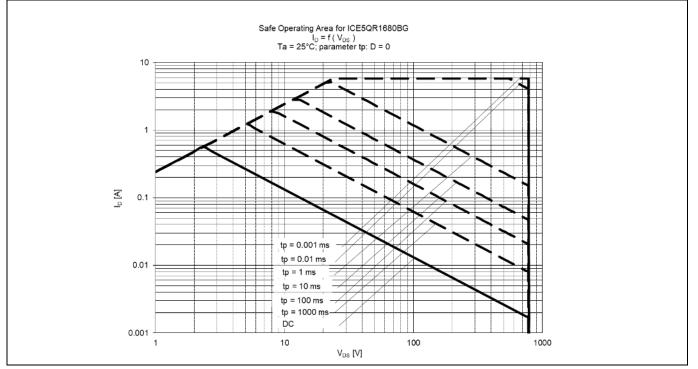


Figure 16 Safe Operating Area (SOA) curve for ICE5QR1680BG

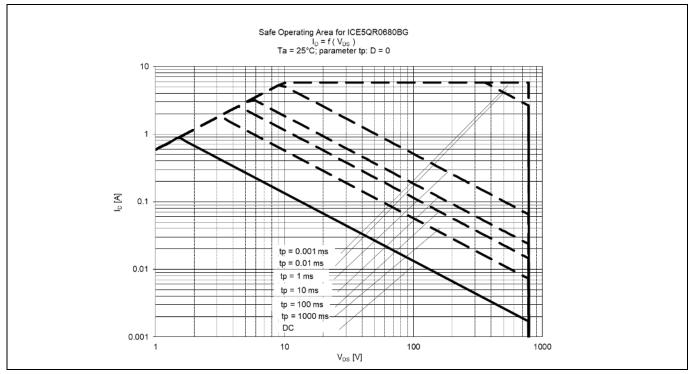
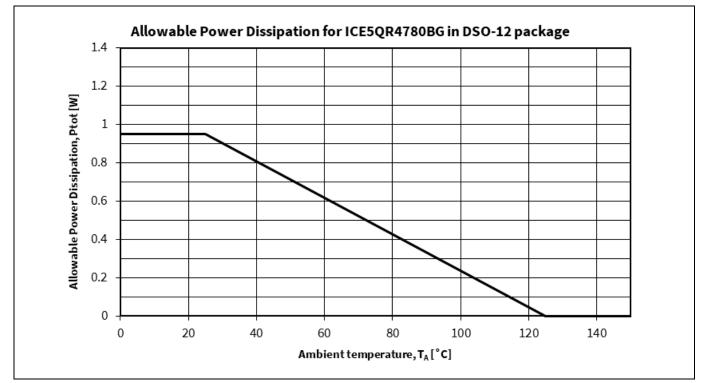
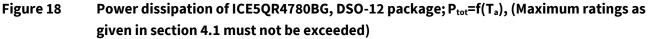


Figure 17 Safe Operating Area (SOA) curve for ICE5QR0680BG







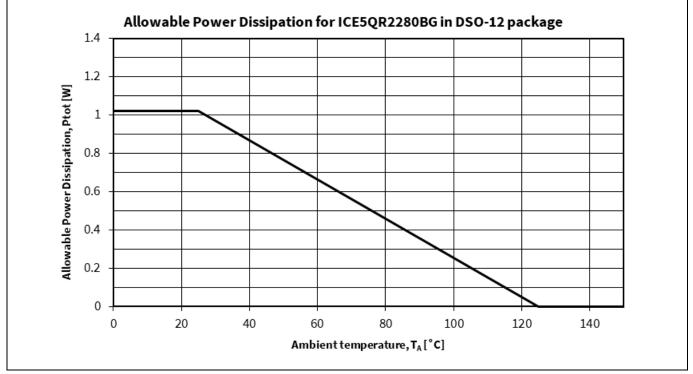
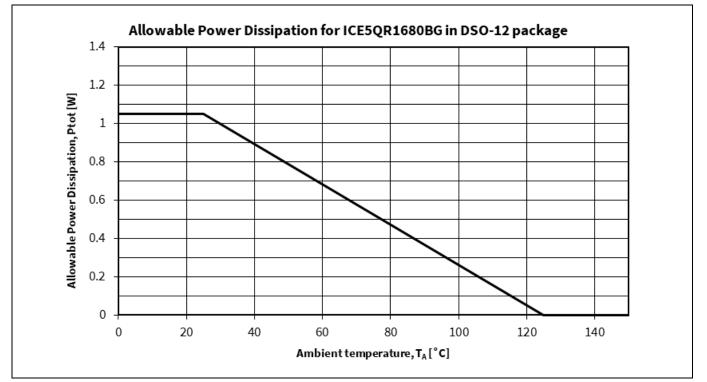
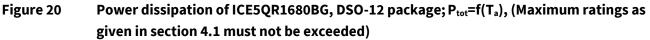


Figure 19Power dissipation of ICE5QR2280BG, DSO-12 package; Ptot=f(Ta), (Maximum ratings as
given in section 4.1 must not be exceeded)







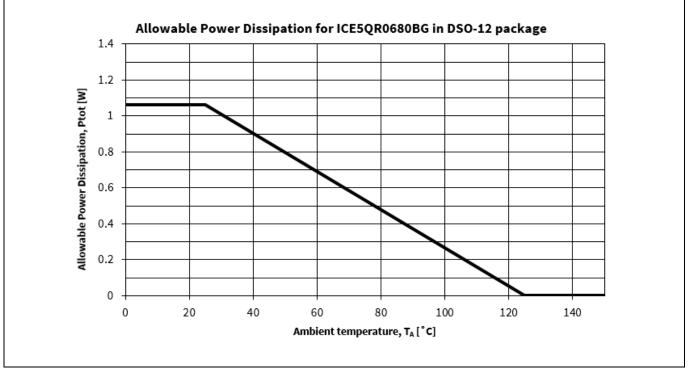
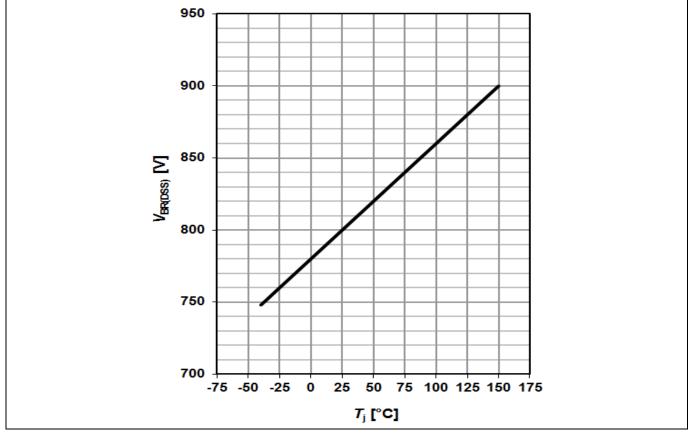
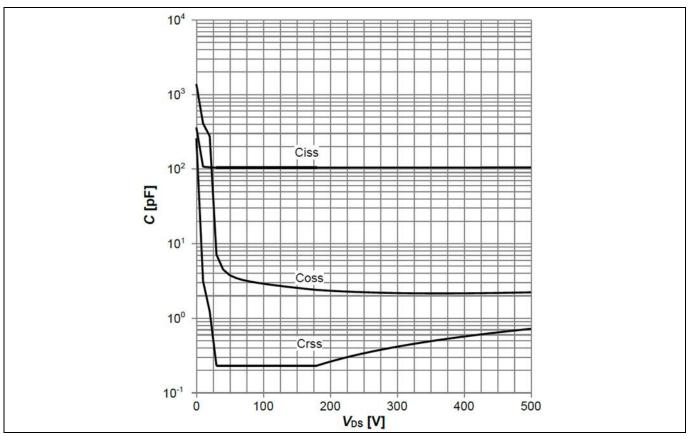


Figure 21Power dissipation of ICE5QR0680BG, DSO-12 package; Ptot=f(Ta), (Maximum ratings as
given in section 4.1 must not be exceeded)



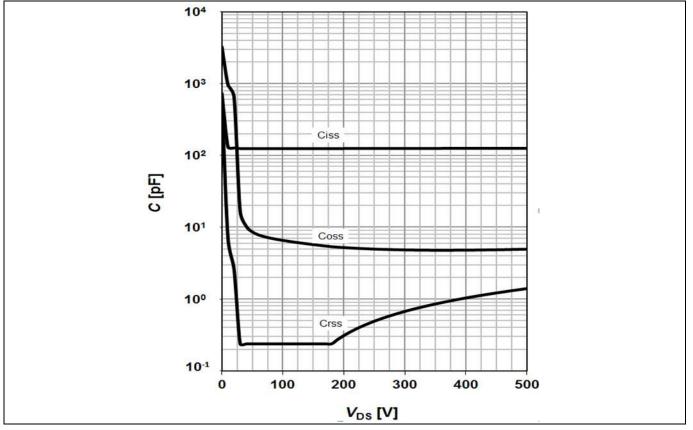




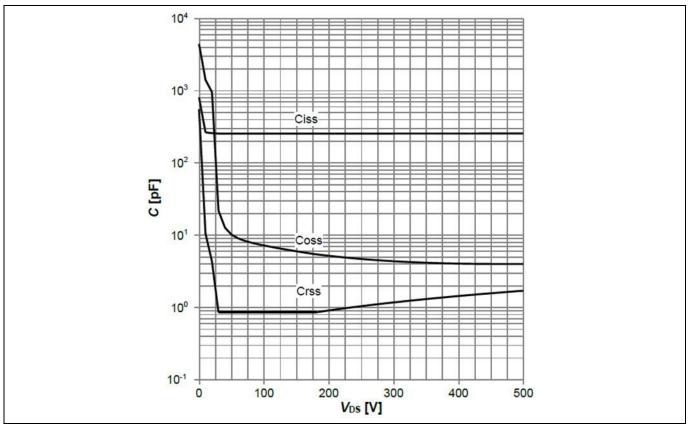
















CoolMOS[™] Performance Characteristics

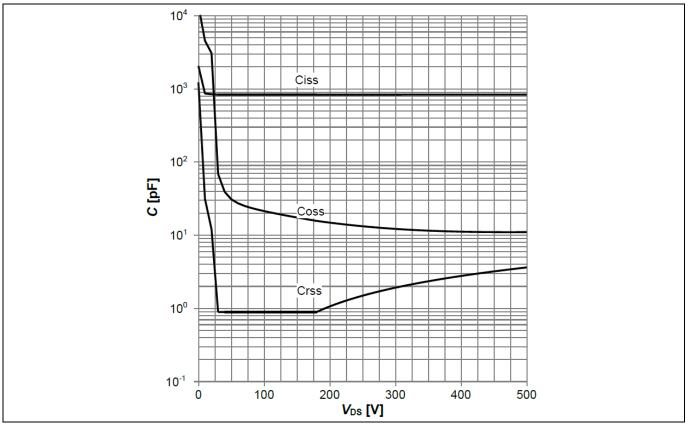


Figure 26 Typical CoolMOS[™] capacitances of ICE5QR0680BG (C=f(V_{DS});V_{GS}=0 V; f=250 kHz)



6 Output Power Curve

The calculated output power curves giving the typical output power versus ambient temperature are shown below. The curves are derived based on a typical discontinuous mode flyback in an open frame design at $T_a=50$ °C, $T_J=125$ °C (integrated high voltage MOSFET), using minimum drain pin copper area in a 2 oz copper single sided PCB and steady state operation only (no design margins for abnormal operation modes are included). The output power figure is for selection purpose only. The actual power can vary depending on particular designs. In a power supply system, appropriate thermal design margins must be applied to make sure that the maximum ratings given in section 4.1 are respected at all times.

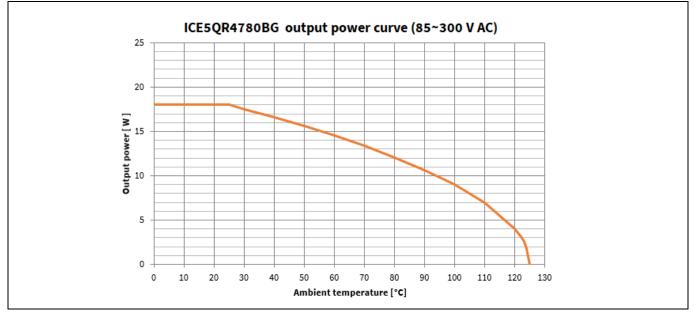


Figure 27 Output power curve of ICE5QR4780BG, V_{IN}=85~300 V_{AC}; P_{out}=f(T_a)

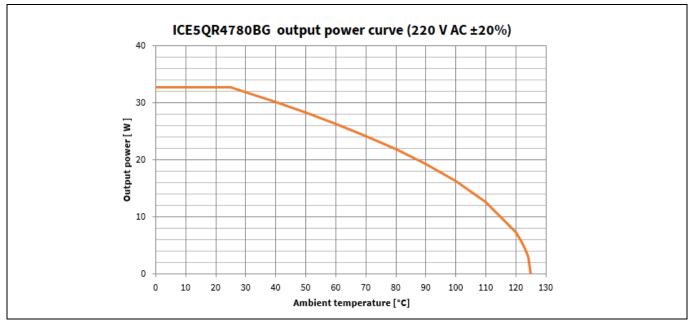


Figure 28 Output power curve of ICE5QR4780BG, V_{IN}=220 V_{AC}; P_{out}=f(T_a)



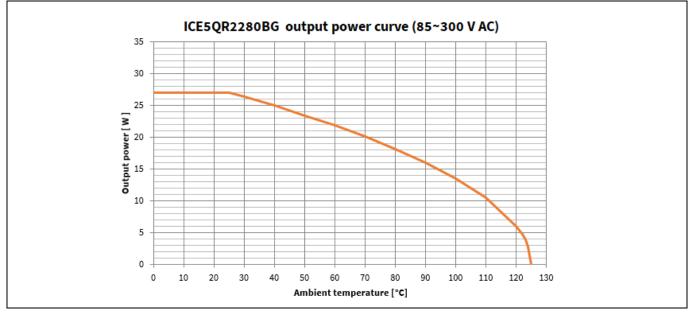


Figure 29 Output power curve of ICE5QR2280BG, V_{IN}=85~300 V_{AC}; P_{out}=f(T_a)

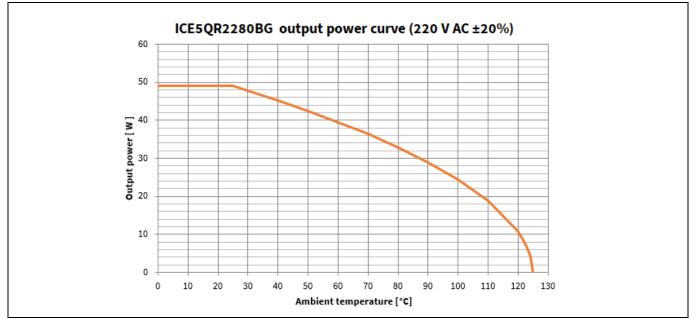


Figure 30 Output power curve of ICE5QR2280BG, V_{IN}=220 V_{AC}; P_{out}=f(T_a)



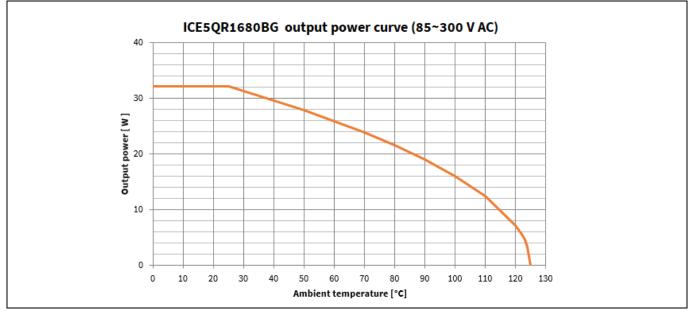


Figure 31 Output power curve of ICE5QR1680BG, V_{IN}=85~300 V_{AC}; P_{out}=f(T_a)

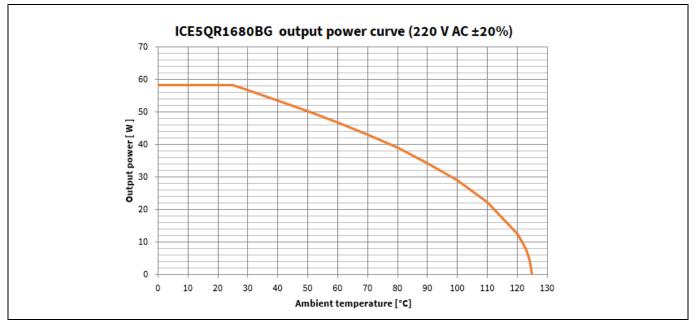


Figure 32 Output power curve of ICE5QR1680BG, V_{IN}=220 V_{AC}; P_{out}=f(T_a)



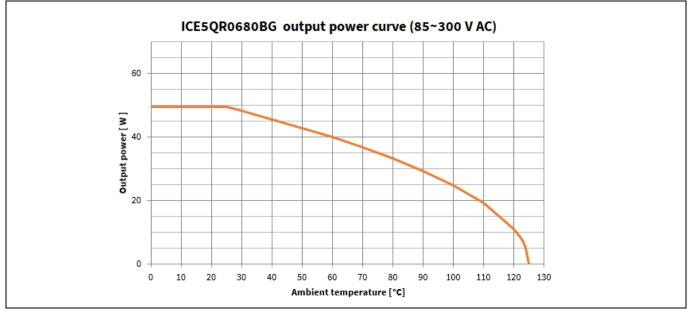


Figure 33 Output power curve of ICE5QR0680BG, V_{IN}=85~300 V_{AC}; P_{out}=f(T_a)

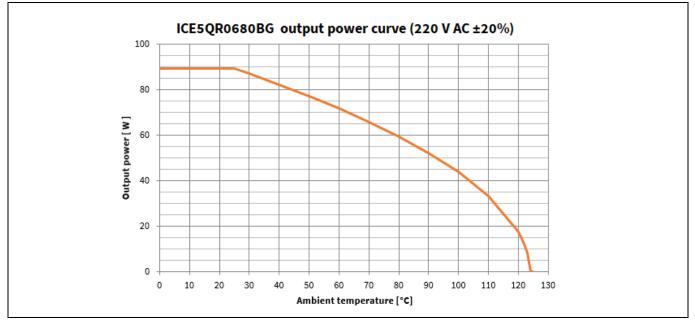


Figure 34 Output power curve of ICE5QR0680BG, V_{IN}=220 V_{AC}; P_{out}=f(T_a)



Outline Dimension



Outline Dimension

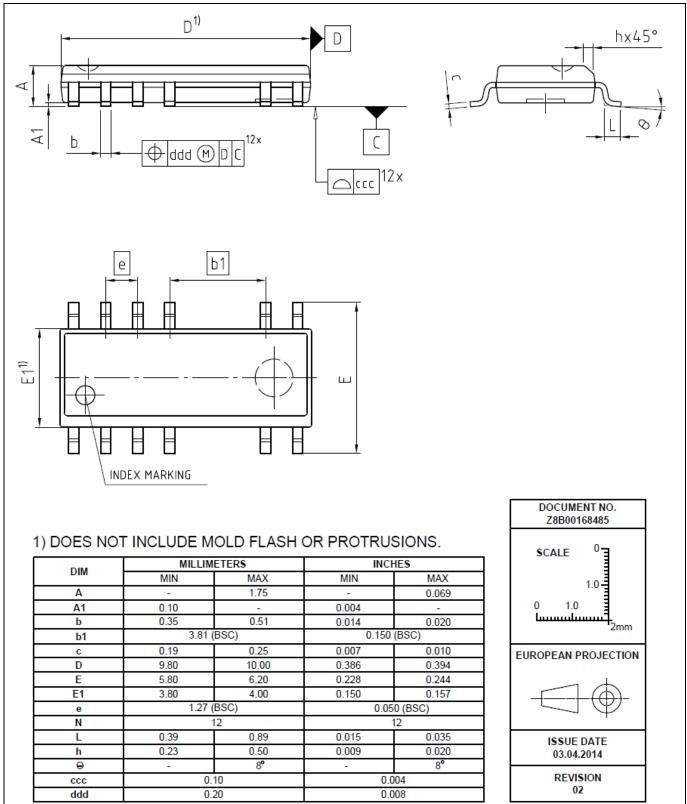
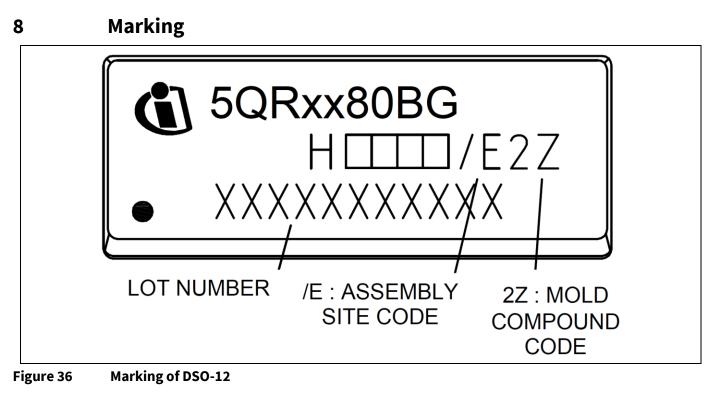


Figure 35

PG-DSO-12



Marking





Revision history

Revision history

Document version	Date of release	Description of changes
V 2.0	30 Aug 2019	First release
V 2.1	21 Jan 2020	 Change the name of datasheet from ICE5QR0680BG to ICE5QRxx80BG to include 3 new variants (ICE5QR4780BG, ICE5QR2280BG and ICE5QR1680BG)
		• Update of CS pin function and description (refer to errata sheet ES_2001_PL83_2002_024629)

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